

REMARKS

Claim 36 is claim 58 copied from the application as filed of the Rinne Patent No. 6,418,033. This claim and others for the same invention were subject to a restriction requirement in that application. Accordingly, in the event a divisional application was filed by Rinne, it is requested that an interference also be declared with such application.

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Claim 36 is readable on the subject disclosure as follows:

A microelectronic packaging method comprising:
orienting a second microelectronic substrate (30, 32 of Fig. 7) at an acute angle (those shown at an acute angle) relative to a first microelectronic substrate (160) such that a plurality of solder bumps (150) extend between the first and second microelectronic substrates, adjacent an edge of the second microelectronic substrate; and

reflowing the plurality of solder bumps to connect the second microelectronic substrate to the first microelectronic substrate while confining the plurality of solder bumps to with the edge of the second microelectronic substrate during reflowing (while reflow of solder balls is standard, the subject specification refers to reflow soldering at page 15, line 17, page 27, line 7, page 30, line 7, page 31, line 9, page 32, line 12 and elsewhere).

It can be seen that the solder bumps are within the edge of the second microelectronic substrate in all of the figures containing solder balls as well as in Figs. 8A to 8C where the terminals 100 which hold the solder balls 140 are shown substantially within the edge of the substrate 94.

The invention as set forth in claim 36 has, ab initio, been the subject matter of the subject application since the only feature not claimed ab initio has been the reflow feature, this being the standard method of attachment of solder balls to a substrate and therefore being inherent in the claims ab initio.



In view of the above remarks and the remarks as set forth in the amendment filed
March 1, 2004, favorable reconsideration and declaration of an interference and/or
interferences as indicated above are respectfully requested.

Respectfully submitted,

A handwritten signature consisting of the letters "J" and "C" connected by a horizontal line.

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